SCLS182C - FEBRUARY 1993 - REVISED APRIL 1996

- EPIC™ (Enhanced-Performance Implanted CMOS) 2-μ Process
- Typical V_{OLP} (Output Ground Bounce)
 < 0.8 V at V_{CC}, T_A = 25°C
- Typical V_{OHV} (Output V_{OH} Undershoot)
 > 2 V at V_{CC}, T_A = 25°C
- ESD Protection Exceeds 2000 V Per MIL-STD-883C, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- Latch-Up Performance Exceeds 250 mA Per JEDEC Standard JESD-17
- Package Options Include Plastic Small-Outline (D), Shrink Small-Outline (DB), Thin Shrink Small-Outline (PW), Ceramic Flat (W) Packages, Chip Carriers (FK), and (J) 300-mil DIPs

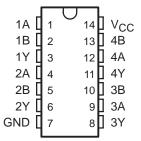
description

These quadruple 2-input positive-NAND gates are designed for 2.7-V to 5.5-V V_{CC} operation.

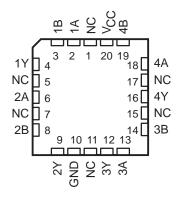
The 'LV00 perform the Boolean function $Y = \overline{A} \cdot \overline{B}$ or $Y = \overline{A} + \overline{B}$ in positive logic.

The SN74LV00 is available in Tl's shrink small-outline package (DB), which provides the same I/O pin count and functionality of standard small-outline packages in less than half the printed-circuit-board area.

SN54LV00 . . . J OR W PACKAGE SN74LV00 . . . D, DB, OR PW PACKAGE (TOP VIEW)



SN54LV00 . . . FK PACKAGE (TOP VIEW)



NC - No internal connection

The SN54LV00 is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74LV00 is characterized for operation from –40°C to 85°C.

FUNCTION TABLE (each gate)

INP	UTS	OUTPUT
Α	В	Y
Н	Н	L
L	X	Н
Х	L	Н



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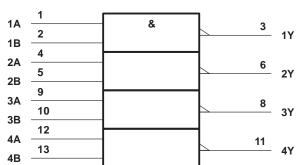


SN54LV00, SN74LV00 QUADRUPLE 2-INPUT POSITIVE-NAND GATES

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logic symbol†

logic diagram, each gate (positive logic)





Pin numbers shown are for D, DB, J, PW, and W packages.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage range, V _{CC}	–0.5 V to 7 V
Input voltage range, V _I (see Note 1)	0.5 V to V _{CC} + 0.5 V
Output voltage range, V _O (see Notes 1 and 2)	0.5 V to V _{CC} + 0.5 V
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$)	±20 mA
Output clamp current, I _{OK} (V _O < 0 or V _O > V _{CC})	
Continuous output current, I_O ($V_O = 0$ to V_{CC})	
Continuous current through V _{CC} or GND	±50 mA
Maximum power dissipation at T _A = 55°C (in still air) (see Note 3): D package	1.25 W
DB or PW	package 0.5 W
Storage temperature range, T _{stq}	–65°C to 150°C

[‡] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
 - 2. This value is limited to 7 V maximum.
 - 3. The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils.

[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

recommended operating conditions (see Note 4)

			SN54	LV00	SN74	LV00	LINUT	
			MIN	MAX	MIN	MAX	UNIT	
Vcc	Supply voltage		2.7	5.5	2.7	5.5	V	
V	High level input valte as	$V_{CC} = 2.7 \text{ V to } 3.6 \text{ V}$	2		2		V	
VIH	High-level input voltage	$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$	3.15		3.15		V	
	$V_{CC} = 2.7 \text{ V to } 3.6 \text{ V}$		0.8		0.8	.,		
VIL	V _{IL} Low-level input voltage	$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$		1.65		1.65	V	
٧ _I	Input voltage		0	Vcc	0	VCC	V	
٧o	Output voltage		0	VCC	0	VCC	V	
		V _{CC} = 2.7 V to 3.6 V	3	-6		-6		
ІОН	High-level output current	$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$	70	-12		-12	mA	
		V _{CC} = 2.7 V to 3.6 V		6		6		
lOL	Low-level output current	V _{CC} = 4.5 V to 5.5 V		12		12	mA	
Δt/Δν	Input transition rise or fall rate	•	0	100	0	100	ns/V	
T _A	Operating free-air temperature		-55	125	-40	85	°C	

NOTE 4: Unused inputs must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

DADAMETED	TEST CONDITIONS		v +	SN54LV00			SN74LV00			LINUT
PARAMETER			v _{cc} †	MIN	TYP	MAX	MIN	TYP	MAX	UNIT
	IOH = -100 μA		MIN to MAX	VCC - 0).2		VCC - 0).2		
Voн	I _{OH} = -6 mA		3 V	2.4			2.4			V
	$I_{OH} = -12 \text{ mA}$		4.5 V	3.6			3.6			
	I _{OL} = 100 μA	I _{OL} = 100 μA				0.2			0.2	
VOL	I _{OL} = 6 mA		3 V		d	0.4			0.4	V
	$I_{OL} = 12 \text{ mA}$		4.5 V		ZE	0.55			0.55	
1.			3.6 V		2	±1			±1	^
II	$V_I = V_{CC}$ or GND		5.5 V		5	±1			±1	μΑ
la a	V- V or CND	1- 0	3.6 V	VO	?	20			20	^
lcc	$V_I = V_{CC}$ or GND	IO = 0	5.5 V	d'a		20			20	μΑ
ΔICC	One input at V _{CC} – 0.6 V	Other inputs at V _{CC} or GND	3 V to 3.6 V			500			500	μΑ
0.	V _I = V _{CC} or GND		3.3 V		2.5			2.5		, F
Ci			5 V		1.5			1.5		pF

[†] For conditions shown as MIN or MAX, use the appropriate values under recommended operating conditions.

switching characteristics over recommended operating free-air temperature range, $C_L = 50 \text{ pF}$ (unless otherwise noted) (see Figure 1)

			SN54LV00								
PARAMETER	FROM (INPUT)	TO (OUTPUT)	VCC	= 5 V ± (0.5 V	Vcc=	= 3.3 V ±	0.3 V	VCC =	2.7 V	UNIT
(INI OT)	(01)	(0011 01)	MIN	TYP	MAX	MIN	TYP	MAX	MIN	MAX	
^t pd	А	Υ		6	11		9	15		18	ns

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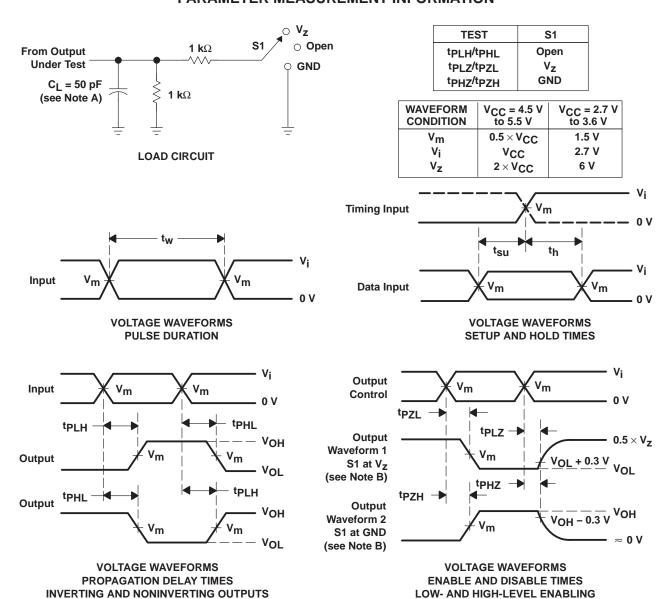
switching characteristics over recommended operating free-air temperature range, C_L = 50 pF (unless otherwise noted) (see Figure 1)

			SN74LV00														
PARAMETER	FROM (INPUT) (TO (OUTPUT)	_	_	-	_	_	_		VCC:	CC = 5 V ± 0.5 V		V_{CC} = 3.3 V \pm 0.3 V		V _{CC} = 2.7 V		UNIT
			MIN	TYP	MAX	MIN	TYP	MAX	MIN	MAX							
t _{pd}	A	Y		6	11		9	15		18	ns						

operating characteristics, $T_A = 25^{\circ}C$

	PARAMETER	TEST CONDITIONS	VCC	TYP	UNIT
		0 50 5 (40 1 1 1	3.3 V	23	_
pd	Power dissipation capacitance per gate	$C_L = 50 \text{ pF}, \qquad f = 10 \text{ MHz}$	5 V	23	pF

PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_O = 50 \ \Omega$, $t_f \leq 2.5 \ ns$.
- D. The outputs are measured one at a time with one transition per measurement.
- E. tpLZ and tpHZ are the same as tdis.
- F. tpzL and tpzH are the same as ten.
- G. tpl H and tpHI are the same as tpd.

Figure 1. Load Circuit and Voltage Waveforms







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PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SN74LV00D	OBSOLETE	SOIC	D	14	TBD	Call TI	Call TI
SN74LV00DBLE	OBSOLETE	SSOP	DB	14	TBD	Call TI	Call TI
SN74LV00DR	OBSOLETE	SOIC	D	14	TBD	Call TI	Call TI
SN74LV00PWLE	OBSOLETE	TSSOP	PW	14	TBD	Call TI	Call TI

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in

a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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